L	Hits	Search Text	DB	Time stamp
Number	}			_
_	14	(barrier adj layer) and (seed adj layer)	USPAT;	2002/12/10
	1	and (release adi layer)	US-PGPUB	09:36
_	73	(method and copper adj	USPAT;	2002/12/06
	, ,	interconnect\$4).ti.	US-PGPUB	13:03
	84	(etch\$3 and copper and dielectric and	USPAT;	2002/12/06
_	}	(barrier adj layer) and (seed adj	US-PGPUB	13:04
Ì	}	layer)).clm.	OS FGFOD	13.04
	309	etch\$3 and ((barrier adj layer) and (seed	USPAT;	2002/12/06
_	309		US-PGPUB	13:10
	100	adj layer)).clm.	USPAT;	2002/12/10
-	482	etch\$3 and (copper adj interconnect\$4)		1
İ	}	and (barrier adj layer) and (seed adj	US-PGPUB	09:50
	l .	layer)	1	2000 (20 (20
-	4	etch\$3 and copper and ((conformal adj	USPAT;	2002/12/10
	Í	dielectric) and (seed adj layer)).clm.	US-PGPUB	07:49
-	288	etch\$3 and copper and ((barrier adj	USPAT;	2002/12/09
	1	layer) and (seed adj layer)).clm.	US-PGPUB	10:55
-	42	copper adj interconnect\$4	JPO	2002/12/10
	l		}	12:23
l -	6	copper adj interconnect\$4	IBM TDB	2002/12/10
İ	i		-	07:56
_	103	(seed adj layer) and damascene adj	USPAT;	2002/12/10
	}	interconnect	US-PGPUB	08:32
l _	99	(damascene adj structure).ti.	USPAT;	2002/12/10
į	1	(damas opino da ja opino da j	US-PGPUB	08:33
_	57	damascene adj structure	JPO	2002/12/10
_	}	damascene adj structure	310	08:33
}	20	interconnect adj structure	JPO	2002/12/10
] =	20	Interconnect adj structure	1020	08:35
ł		(barrier adj layer) and (seed adj layer)	USPAT;	2002/12/10
-	3	(barrier ad) layer) and (seed ad) layer)	US-PGPUB	09:13
1	}	and photosensitive adj dielectric	1	
-	5	photosensitive near5 (FSG or OSG or HSQ)	USPAT;	2002/12/10
]			US-PGPUB	09:30
-	66	(phosphoric adj acid) same (nitric adj	USPAT;	2002/12/10
	}	acid) same (acetic adj acid) same part	US-PGPUB	09:40
	1	same (etch\$3 or CMP)	}	1 ((
-	76	(dielectric adj layer) and (aluminum adj	USPAT;	2002/12/11
}	}	layer) and (barrier adj layer) and (seed	US-PGPUB	08:29
l	1	adj layer)		(
_	93	(copper adj interconnect\$4) and (void adj	USPAT;	2002/12/11
	{	formation)	US-PGPUB	08:46
_	13	(conformal adj dielectric) and (barrier	USPAT;	2002/12/11
)	1	adj layer) and (seed adj layer)	US-PGPUB	08:39
_	14		USPAT;	2002/12/11
		((void adj formation) or (ion adj	US-PGPUB	08:47
	{	migration))		,
	3	damascene same sidewall adj dielectric	USPAT;	2002/12/11
_)	damascone same sidewail ad dicteorito	US-PGPUB	10:15
	1	<u> </u>	JU EGEOD	1 + 2 + 4 2